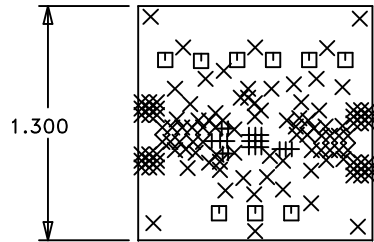


DO NOT SCALE PRINT

REVISION				
ZONE	LTR	DESCRIPTION	DATE	APPROVED
	1	ENGINEERING RELEASE	12/18/09	V. LY



HITTITE MICROWAVE  
PCB #128683-1  
DRILL DRAWING

SIZE	QTY	SYM	PLATED	TOL
10	19	+	YES	+/-3
14	115	X	YES	+/-3
63	9	□	YES	+/-3

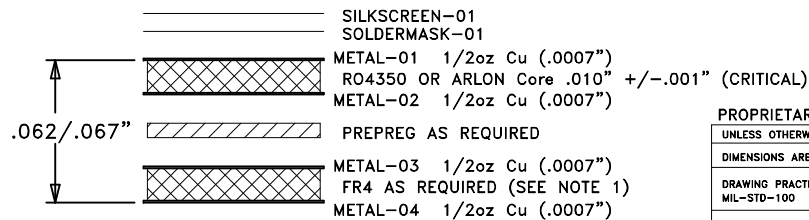
#### NOTES:

#### UNLESS OTHERWISE SPECIFIED

1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350 OR ARLON 25FR, HALF OUNCE COPPER BOTH SIDES. FR4 TO BE USED AS FILLER TO MEET CRITICAL OVERALL THICKNESS.
2. FINISH: GOLD PLATE PER ASTM B-488, TYPE III, CODE A, 8 TO 40 MICROINCHES, OVER NICKEL PER QQ-N-290, 100 MICROINCHES MINIMUM.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN  $\pm 0.003$ " OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION  $\pm 0.003$ " MAX.
7. BOARD WARPAGE:  $< 0.010$ " PER LINEAR INCH.
8. SILKSCREEN TOPSIDE ONLY WITH WHITE EPOXY INK.
9. PLATING THICKNESS  $.002 \pm 0.0005$  FOR METAL-01 AND METAL-04.
10. SOLDERMASK: LPI SOLDERMASK TOP SIDE. COLOR: GREEN REGISTRATION:  $\pm 0.004$  MAX.
11. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPARATION.
12. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.
13. "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
14. MANUFACTURE PER IPC-6012 CLASS 2.

#### UNLESS OTHERWISE SPECIFIED

15. CRITICAL LINE WIDTH =  $.016 \pm 0.001$  ADJUST PROCESS TO ACHIEVE WIDTH.



#### LAYER STACKUP

#### PROPRIETARY TO HITTITE MICROWAVE CORPORATION

UNLESS OTHERWISE SPECIFIED:

DIMENSIONS ARE IN INCHES (MM)

DRAWING PRACTICES PER  
MIL-STD-100

TOLERANCES:

.XX	+/- 0.010
.XXX	+/- 0.005
.XXXX	+/- 0.002
ANGLES	+/- .5 DEG

DWN BY:

V. LY 12/17/09

ENGINEER:

A. EKEN 12/18/09



HITTITE MICROWAVE CORPORATION  
20 Alpha Road Chelmsford, MA 01824

TITLE  
PCB, SINGLE ENDED EVAL  
HMC5628LP4

SIZE	CODE ID NO.	DRAWING NO.	REV
A	1CN88	128683	1
SCALE: NONE		WT	SHEET 1 of 1